

ABSTRACT

A carrier for polishing processing is made of a composite material including fibers oriented in at least a certain direction and a resin material, and has a holding hole for holding a disk-shaped substrate when a pair of main surfaces of the substrate are subjected to polishing processing with the substrate sandwiched between an upper surface plate and a lower surface plate. The holding hole has, on a circumference of an inner circumferential wall surface of the holding hole, a first wall portion that is configured such that the substrate is in contact with the fibers in a state in which the substrate is held in the holding hole, and a second wall portion that is configured such that the substrate does not come into contact with the fibers. The second wall portion is formed in a portion of the inner circumferential wall surface facing toward an orientation direction of the fibers that includes the certain direction.

[Fig. 4]